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### (54) TRANSCEIVER HANDLE HEAT DISSIPATION AIRFLOW CHANNELING **SYSTEM**

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#### (57)ABSTRACT

A transceiver handle heat dissipation airflow channeling system includes a transceiver device having a transceiver device chassis, at least one heat producing component that is housed in the transceiver device chassis, and a transceiver device handle that extends from the transceiver device chassis and that defines an airflow channel along its length. The transceiver device handle receives airflow at an airflow channel entrance defined by the transceiver device handle, directs the airflow through the airflow channel, and dissipates heat generated by the heat producing component(s) using the airflow directed through the airflow channel. For example, the airflow may be directed through the airflow channel and adjacent the heat producing component(s) in the transceiver device chassis, adjacent a heat dissipation device that is integrated with the transceiver device chassis, or adjacent a heat dissipation device that extends from a transceiver device port to which the transceiver device is connected.

